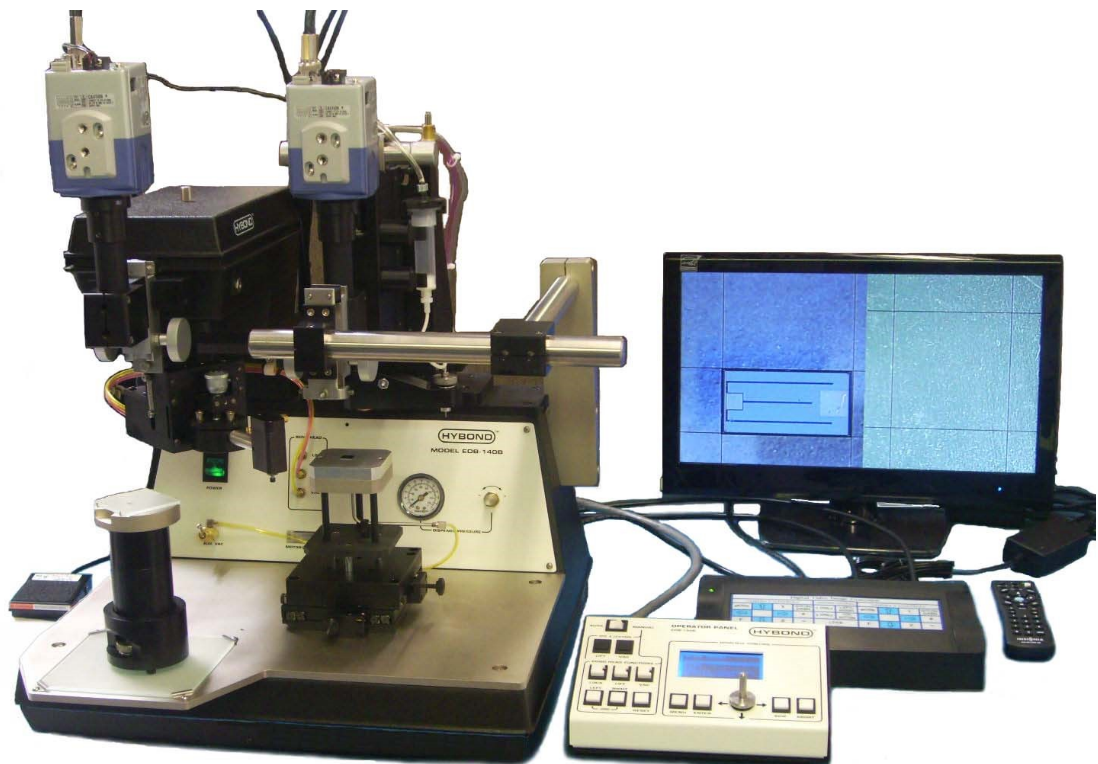
HYBOND

MODEL EDB-140B

EPOXY/SILVER GLASS DIE BONDER



STANDARD FEATURES:

- Color CCTV system (as shown).
- Package depth sensing for consistent and precise bond line thickness.
- Built-in programmable dispense control.
- Storage for up to 200 dispense programs.
- Manual X-Y alignment stage.
- Waffle pack/loose die pick up pedestal.
- Pitch and roll adjustment for bond head.
- Custom dispense heads/dispense patterns.
- Custom die collets to match customer die.
- Manual and semi-automatic operation modes.
- Remote control panel for ease of operation.

HYBOND's Model EDB-140B is a semiautomatic epoxy/silver glass die bonder which provides uniform epoxy or silver glass dispensing with consistent material thickness and precise die placement. The EDB-140B can be fitted with a waffle pack/gel pack or loose die pedestal or a die ejector for holding die on wafers. The dispense system can be fitted with HYBOND's micro-dispense head or epoxy daubing/stamping system for extremely low volume epoxy application. This die bonder is rugged enough for continuous production and ideal for small to medium production runs and laboratory applications. Die pick up and placement are made easy with the aid of dual CCTV cameras and a split screen monitor which incorporates a die and package visual targeting system. The EDB-140B is modular and easily adapts to modifications to accommodate fixturing for custom packages.

Partial List of Available Options:

- Die ejector systems.
- Zoom stereo microscope with swivel base.
- Dual fiber optic illumination system.
- Stir column for silver glass/conductive epoxy.
- Daubing/stamping system.
- Micro-dispensing head.
- Lead frame indexing systems.
- Semi-automatic indexing systems.
- Heater stage and temperature controller.
- Customization based on specific application.

Model EDB-140B Specifications:

- Dispense System: Programmable pressure, time and suck-back (avoids drip) system.
- Bond Line Accuracy: +/-0.5mil (+/-12,7um).
- Temperature Control Range: Ambient.
- Bondable Die Size Range: 6x6 mils (152x152um) to 1x1in (25,4 x 25,4mm) standard.
- Placement Accuracy: +/-1mil (25,4um) standard. Optional +/- 0.2 mil (5um) available.
- Dispense Materials: Epoxy, conductive epoxy and silver glass.
- Bond Head Movement: Motorized, rotational with fixed pickup and placement points.
- Bond Actuation: By opto-sensor at fixed height. Cycle initiated by footswitch.
- Z Travel/Vertical Bonding Window: 0.5in (12mm)/0.125 to 0.500in (3mm to 12mm).
- Table Motion: Manual, with thumbscrews, standard.
- Input Power Requirements: 120 VAC 50/60Hz @ 5A max. (more if adding heated stage).
- Minimum Bench Space Required: Height/width: 24in. (61cm), Depth: 22in. (56cm), without monitor.
- Facilities Required (minimum): Vacuum: 23in.Hg (584mmHg). Air: 70-80psi (4,93-5,64 Kg/cm^2).
- Unit Weight/Shipping Weight: 75lbs (34Kg)/150lbs (68Kg). Shipping weight will vary.
- Approximate Units Per Hour (UPH): 90 - 240 depending on options, settings and mode of operation.

For more information contact us:

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